



## Material Content Data Sheet



Sales Product Name	BTS54220-LBA			Issued		29. August 2013		
MA#	MA001141616							
Package	PG-TSON-24-3			Weight*		184.25 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	10.076	5.47	5.47	54689	54689
leadframe	inorganic material	phosphorus	7723-14-0	0.021	0.01		114	
	non noble metal	zinc	7440-66-6	0.084	0.05		457	
	non noble metal	iron	7439-89-6	1.685	0.91		9146	
	non noble metal	copper	7440-50-8	68.425	37.14	38.11	371373	381090
wire	non noble metal	copper	7440-50-8	2.586	1.40	1.40	14037	14037
encapsulation	organic material	carbon black	1333-86-4	0.183	0.10		994	
	plastics	epoxy resin	-	9.428	5.12		51168	
	inorganic material	silicondioxide	60676-86-0	81.920	44.46	49.68	444616	496778
leadfinish	non noble metal	tin	7440-31-5	2.547	1.38	1.38	13821	13821
plating	noble metal	silver	7440-22-4	0.378	0.21	0.21	2052	2052
solder	noble metal	silver	7440-22-4	0.173	0.09		938	
	non noble metal	tin	7440-31-5	0.138	0.08		751	
	non noble metal	lead	7439-92-1	6.604	3.58	3.75	35844	37533
*deviation	< 10%	Sum in total:			100,00			1000000

### Important Remarks:

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